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(71) Applicant (for all designated States except US): OPTILION AB [SE/SE]; Box 47646, S-117 94 Stockholm (SE).

(72) Inventors; and

(75) Inventors/Applicants (for US only): STOLTZ, Björn [SE/SE]; Birger Jarlsgatan 102A, S-114 20 Stockholm (SE). BENDZ, Eskil [SE/SE]; Vikingagatan 26, S-113 42 Stockholm (SE).

(74) Agent: EHRNER & DELMAR PATENTBYRÅ AB; Box 103 16, S-100 55 Stockholm (SE).

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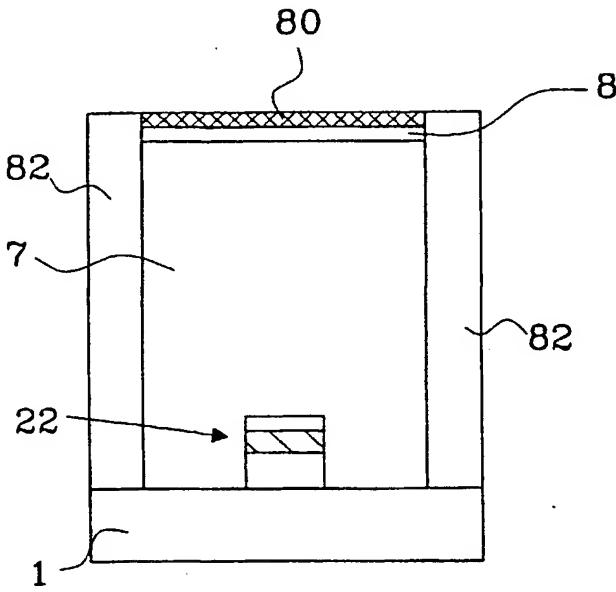
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(54) Title: METHOD FOR MANUFACTURING A PHOTONIC DEVICE AND A PHOTONIC DEVICE



(57) Abstract: The present invention relates to a photonic device having a first set of layers (22) including at least a first waveguide layer (3) arranged in a waveguide mesa (61). A cladding layer (7) is arranged on top of the waveguide mesa (61) and surrounding semiconductor material (1). A contact layer (8) is arranged on top of the cladding layer (7), and a metal contact (9, 80) is arranged on top of the contact layer (8). The cladding (7) and contact (8) layer are shaped in an etching process to have a mesa structure at least above the waveguide mesa (61). An insulating material (25, 82) is also applied around the mesa structure. Optionally a second photonic device having a second set of layers (31) including at least a second waveguide layer (33), may be coupled to the first photonic device in a light transmission direction thereof. The invention also relates to a method for manufacturing the photonic device.